

O2 HEADPHONE AMPLIFIER POWER MANAGEMENT LATCH BILL OF MATERIALS (BOM)

agdr on diyaudio.com, 2014

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part	purpose		mfgr	mfgr number	Mouser	each	ttl	Digikey (alt = substitution)	each	
dual comparator, VSSOP8 SMD package	comparator, equivalent to NJM2903D	1	IC1	TI	LM2903DGKR	595-LM2903DGKR	\$0.41	\$0.41	296-16806-1-ND	\$0.42
2N7002 n-channel mosfets, SOT23	relay circuit switching mosfets	2	Q1, Q2	ON semi	2N7002LT1G	863-2N7002LT1G	\$0.15	\$0.30	2N7002LT3GOSCT-ND	\$0.15
2.2uF 50V 10% X7R MLCC 1206 SMD	decoupling caps for the op amps and current buffers	1	C1	murata	GRM31CR71H225KA88L	81-GRM31CR71H225KA88	\$0.34	\$0.34	490-3367-1-ND	\$0.38
4.7 meg 0.1% 1/8W 25PPM/K 1206 SMD thin film	Input ground return resistors	1	R1	susumu	RG3216P-1004-B-T5	754-RG3216P-1004-BT5	\$0.65	\$0.65	RG32P1.0MBCT-ND	\$0.65
PC board 4 layer, in QTY 5, each		1		Seeed	Fusion 4 layer 1.6mm 50mmx100mm		\$5.00	\$5.00		
Dual pluggable SIP headers, 0.335" extension posts	connection posts to the O2 PC board. For the B2-080 standard O2 case.	1	JP1, JP2	mill max					ED17064-ND	

GRAND TOTAL

\$6.70